

Material Content Data Sheet

RoHS

Sales Product Name	TLE4926C-HT E6547	**Issued**	28. August 2013
MA#	MA000727182		
Package	PG-SSO-3-92	**Weight***	159.74 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.277	1.43	1.43	14252	14252
leadframe	non noble metal	chromium	7440-47-3	0.240	0.15		1501	
	non noble metal	titanium	7440-32-6	0.240	0.15		1501	
	noble metal	silver	7440-22-4	0.320	0.20		2001	
	non noble metal	tin	7440-31-5	0.479	0.30		3001	
	non noble metal	copper	7440-50-8	78.632	49.21	50.01	492239	500243
wire	noble metal	gold	7440-57-5	0.045	0.03	0.03	285	285
encapsulation	organic material	carbon black	1333-86-4	0.426	0.27		2667	
	plastics	brominated resin	-	0.532	0.33		3333	
	inorganic material	antimonytrioxide	1309-64-4	1.065	0.67		6666	
	plastics	epoxy resin	-	9.691	6.07		60664	
	inorganic material	silicondioxide	60676-86-0	41.532	26.00	33.34	259987	333317
leadfinish	non noble metal	tin	7440-31-5	5.565	3.48	3.48	34837	34837
plating	noble metal	silver	7440-22-4	0.442	0.28	0.28	2767	2767
glue	plastics	epoxy resin	-	0.147	0.09		921	
	noble metal	silver	7440-22-4	0.589	0.37	0.46	3686	4607
smd	plastics	epoxy resin	-	0.004	0.00		25	
	noble metal	palladium	7440-05-3	0.466	0.29		2919	
	noble metal	silver	7440-22-4	0.550	0.34		3440	
	non noble metal	copper	7440-50-8	1.210	0.76		7574	
	non noble metal	nickel	7440-02-0	1.513	0.95		9469	
	inorganic material	bariumtitanate	12047-27-7	13.780	8.63	10.97	86265	109692
*deviation	< 10%				Sum in total:	100,00		1000000

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